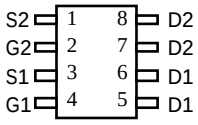
ALPHA & OMEGA SEMICONDUCTOR

AOP608
Complementary Enhancement Mode Field Effect Transistor

General Description
The AOP608 uses advanced trench technology MOSFETs to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used in H-bridge, Inverters and other applications. *Standard Product AOP608 is Pb-free (meets ROHS & Sony 259 specifications). AOP608L is a Green Product ordering option. AOP608 and AOP608L are electrically identical.*

Features
n-channel	p-channel
V_{DS} (V) = 40V	-40V
I_D = 6.3A (V_{GS}=10V)	-5.5A (V_{GS} = -10V)
$R_{DS(ON)}$	$R_{DS(ON)}$
< 33mΩ (V_{GS}=10V)	< 45mΩ (V_{GS} = -10V)
< 46mΩ (V_{GS}=4.5V)	< 63mΩ (V_{GS} = -4.5V)



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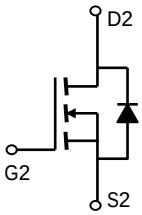
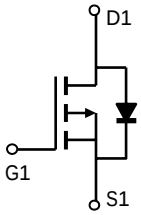


n-channel



p-channel

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Max n-channel	Max p-channel	Units
Drain-Source Voltage		V_{DS}	40	-40	V
Gate-Source Voltage		V_{GS}	±20	±20	V
Continuous Drain Current [A]	T_A=25°C	I_D	6.3	-5.5	A
	T_A=70°C		5	-4.4	
Pulsed Drain Current [B]		I_{DM}	20	-20	
Power Dissipation	T_A=25°C	P_D	2.5	2.5	W
	T_A=70°C		1.6	1.6	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	-55 to 150	°C

Thermal Characteristics: n-channel and p-channel

Parameter		Symbol	Device	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	n-ch	37	50	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		n-ch	74	90	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	n-ch	28	40	°C/W
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	p-ch	35	50	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		p-ch	73	90	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	p-ch	32	40	°C/W

N Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	40			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=32V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}= ±20V			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	1	2.3	3	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V	20			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=6.3A		24.1	33	mΩ
		T_J=125°C		40		
		V_{GS}=4.5V, I_D=5A		33.7	46	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=6.3A		22		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.77	1	V
I_S	Maximum Body-Diode Continuous Current				6.3	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=30V, f=1MHz		404		pF
C_{oss}	Output Capacitance			95		pF
C_{rss}	Reverse Transfer Capacitance			37		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		2.7		Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=20V, I_D=6.3A		9.2		nC
Q_g(4.5V)	Total Gate Charge			4.6		nC
Q_{gs}	Gate Source Charge			1.6		nC
Q_{gd}	Gate Drain Charge			2.5		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=20V, R_L=3Ω, R_{GEN}=3Ω		4.3		ns
t_r	Turn-On Rise Time			3.4		ns
$t_{D(off)}$	Turn-Off DelayTime			15		ns
t_f	Turn-Off Fall Time			2.8		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=6.3A, dI/dt=100A/µs		21.2		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=6.3A, dI/dt=100A/µs		15.8		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80µs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: N-CHANNEL

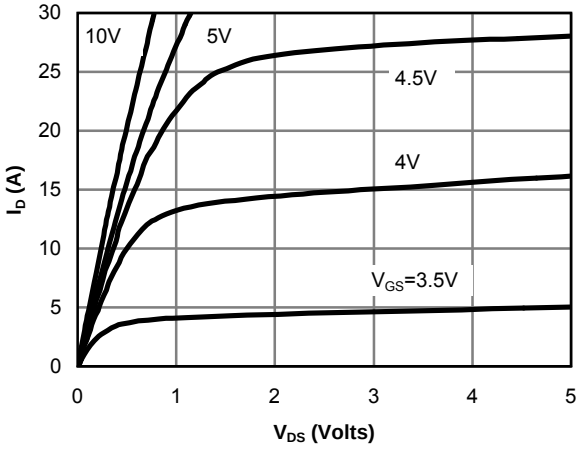

Fig 1: On-Region Characteristics

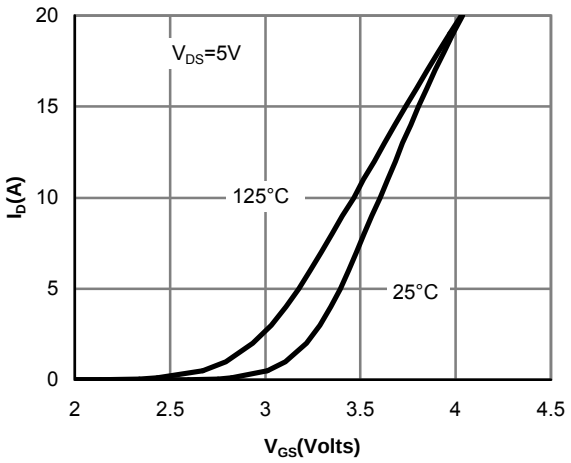

Figure 2: Transfer Characteristics

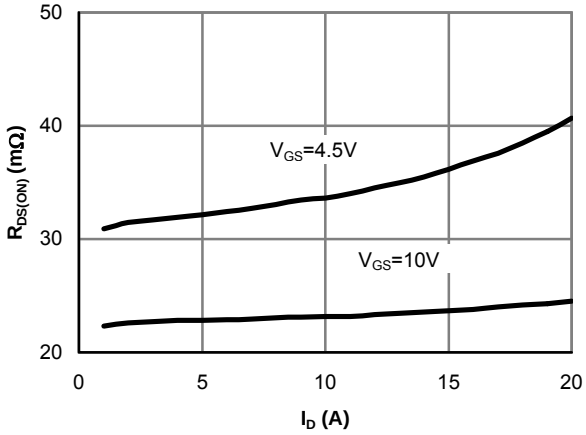

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

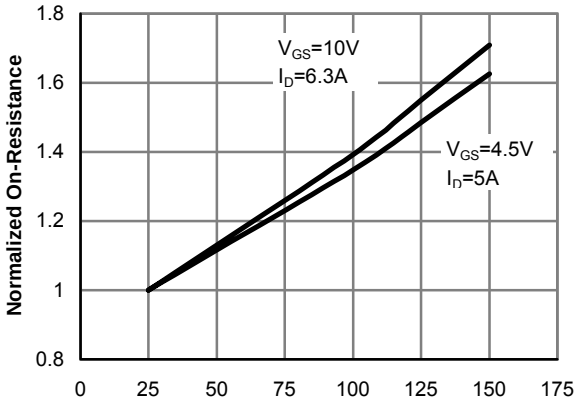

Figure 4: On-Resistance vs. Junction Temperature

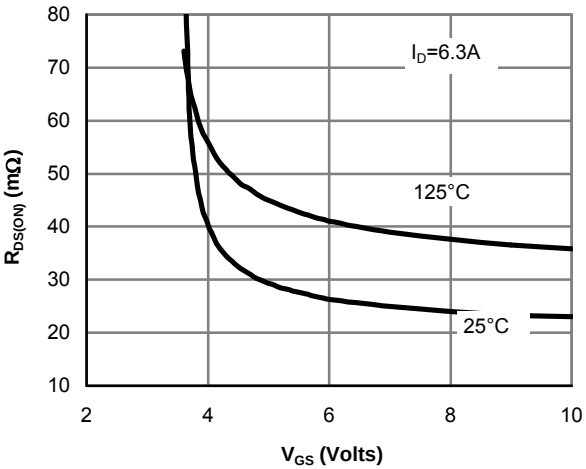

Figure 5: On-Resistance vs. Gate-Source Voltage

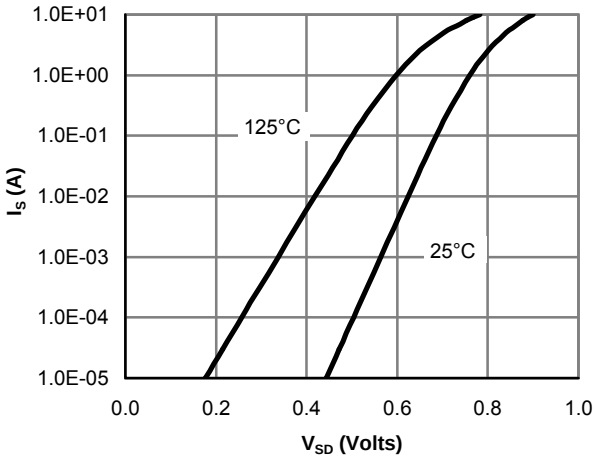

Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: N-CHANNEL

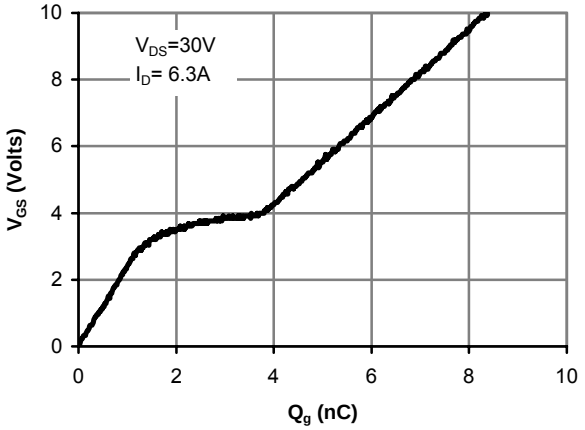

Figure 7: Gate-Charge Characteristics

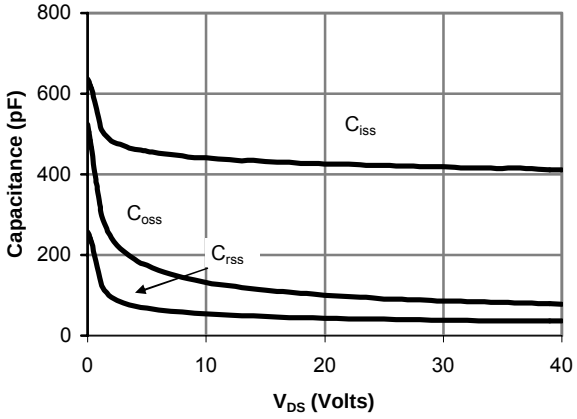

Figure 8: Capacitance Characteristics

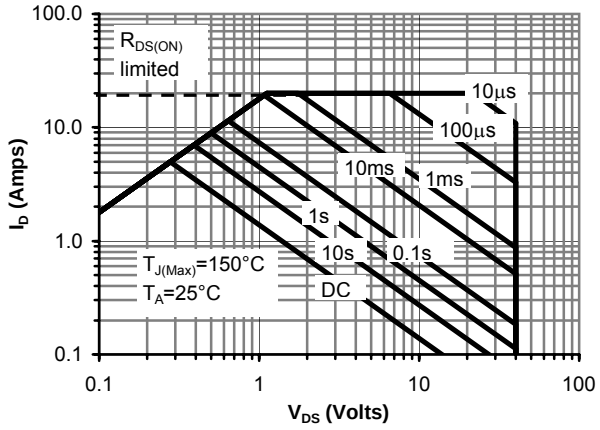

Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

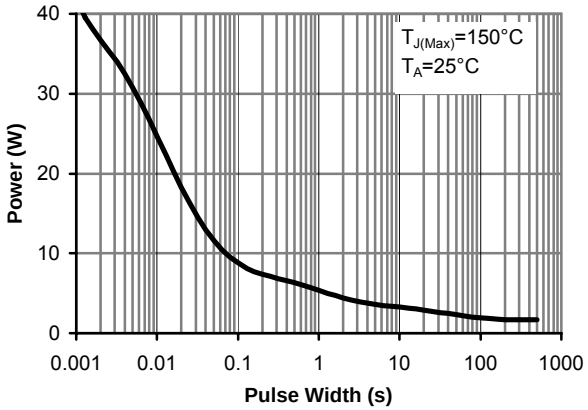

Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

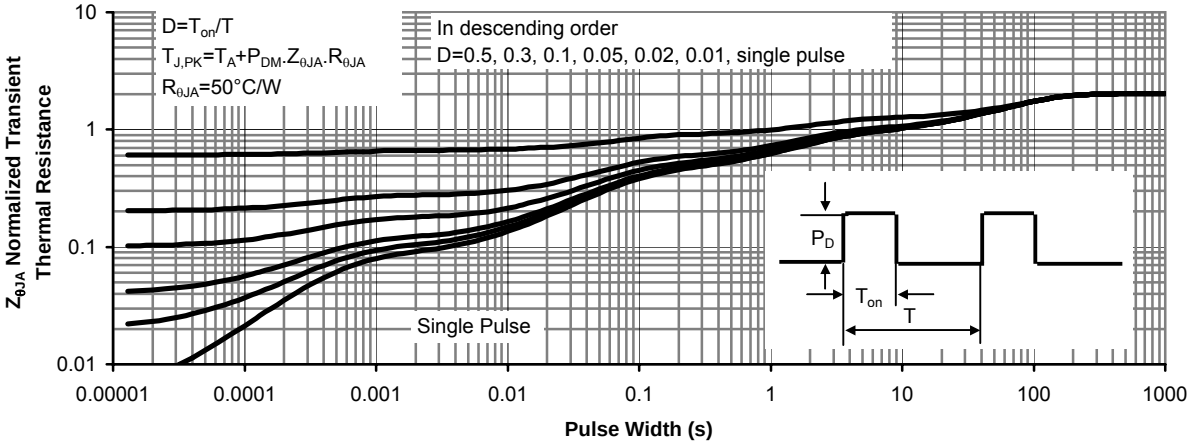

Figure 11: Normalized Maximum Transient Thermal Impedance

P-Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=-250µA, V_{GS}=0V	-40			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-32V, V_{GS}=0V			-1	µA
		T_J=55°C			-5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=-250µA	-1	-1.9	-3	V
$I_{D(ON)}$	On state drain current	V_{GS}=-10V, V_{DS}=-5V	-20			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-10V, I_D=-5.5A		34.7	45	mΩ
		T_J=125°C		56	70	
		V_{GS}=-4.5V, I_D=-4.6A		50.6	63	mΩ
g_{FS}	Forward Transconductance	V_{DS}=-5V, I_D=-5.5A		12		S
V_{SD}	Diode Forward Voltage	I_S=-1A,V_{GS}=0V		-0.75	-1	V
I_S	Maximum Body-Diode Continuous Current				-5.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-20V, f=1MHz		657		pF
C_{oss}	Output Capacitance			143		pF
C_{rss}	Reverse Transfer Capacitance			63		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		6.5		Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge (10V)	V_{GS}=-10V, V_{DS}=-20V, I_D=-5.5A		14.2		nC
Q_g(4.5V)	Total Gate Charge (4.5V)			7.1		nC
Q_{gs}	Gate Source Charge			2.2		nC
Q_{gd}	Gate Drain Charge			4.1		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=-10V, V_{DS}=-20V, R_L=3.6Ω, R_{GEN}=3Ω		7.7		ns
t_r	Turn-On Rise Time			8		ns
$t_{D(off)}$	Turn-Off DelayTime			26.5		ns
t_f	Turn-Off Fall Time			11.5		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=-5.5A, dI/dt=100A/µs		21.9		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=-5.5A, dI/dt=100A/µs		14.9		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80µs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

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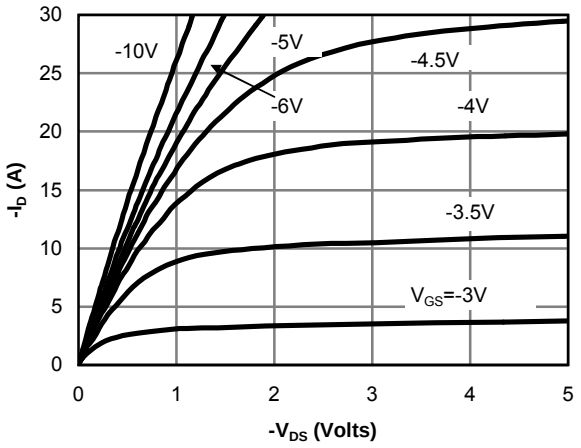
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: P-CHANNEL



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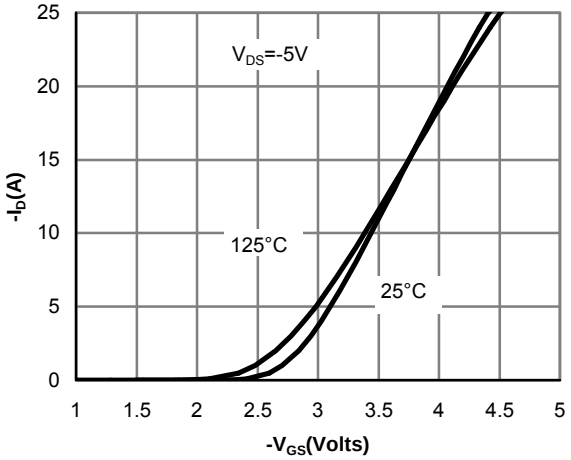

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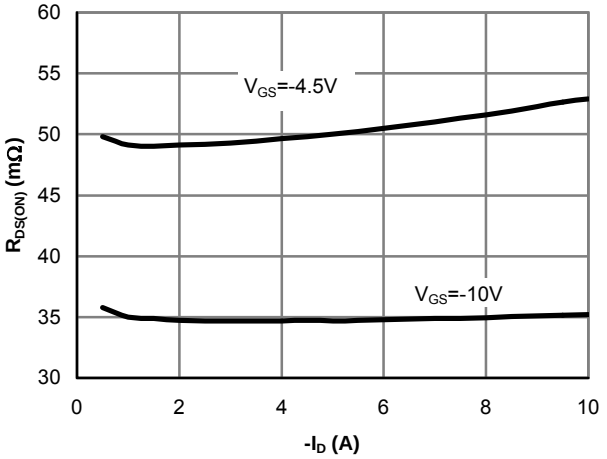

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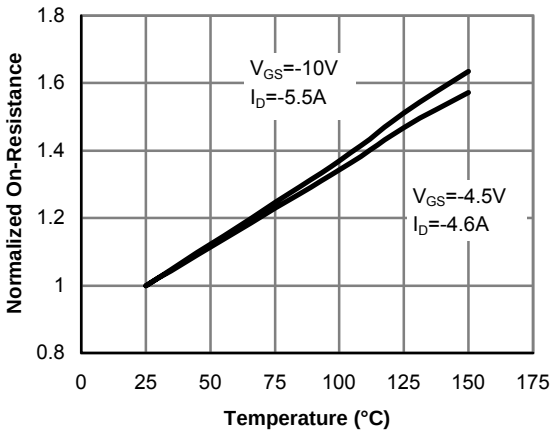

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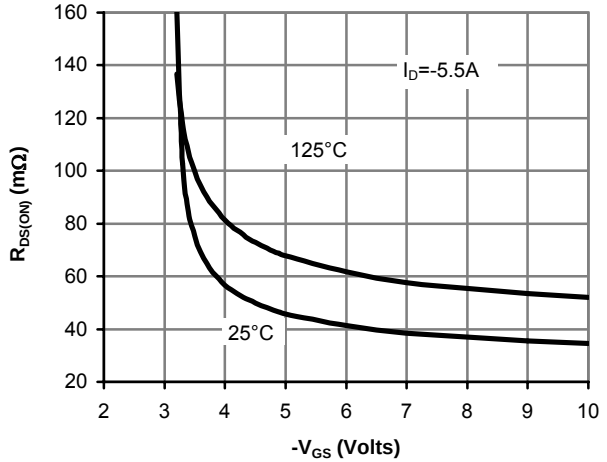

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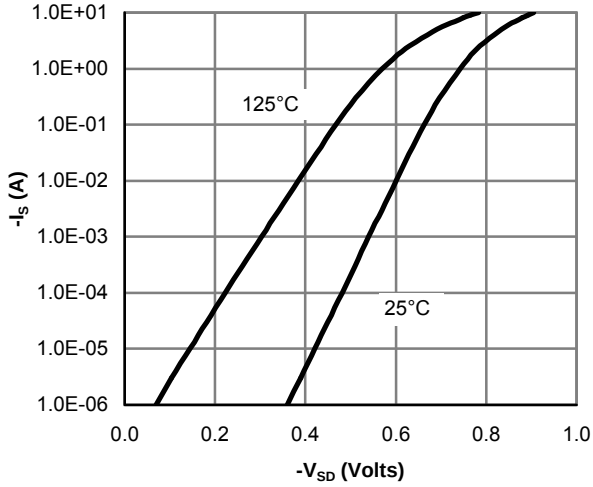

Figure 6: Body-Diode Characteristics

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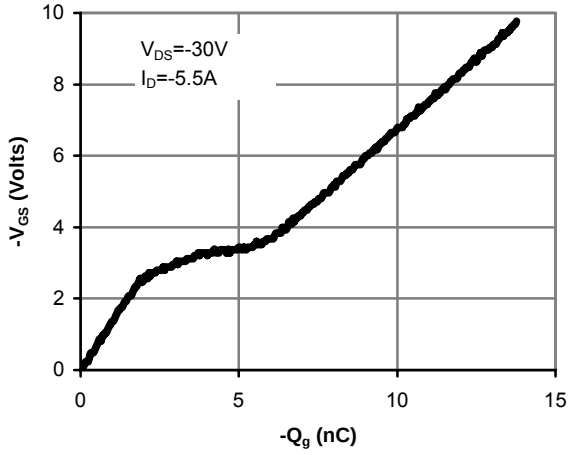

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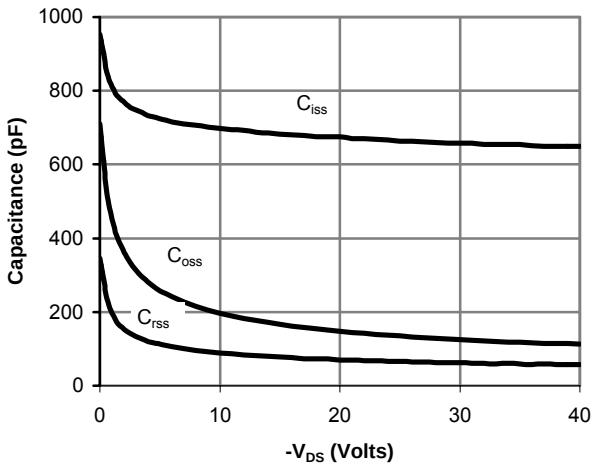

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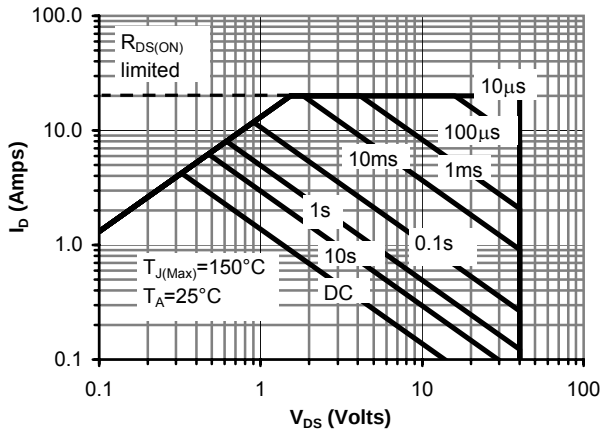

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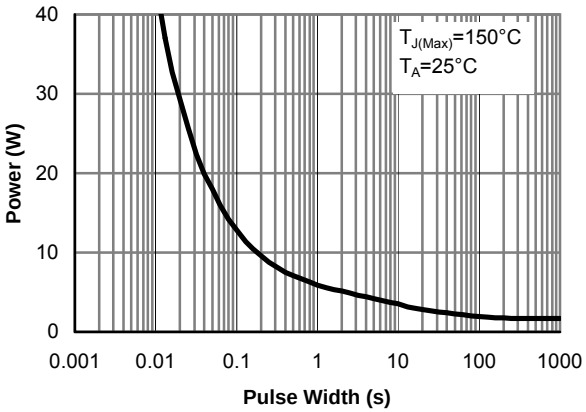

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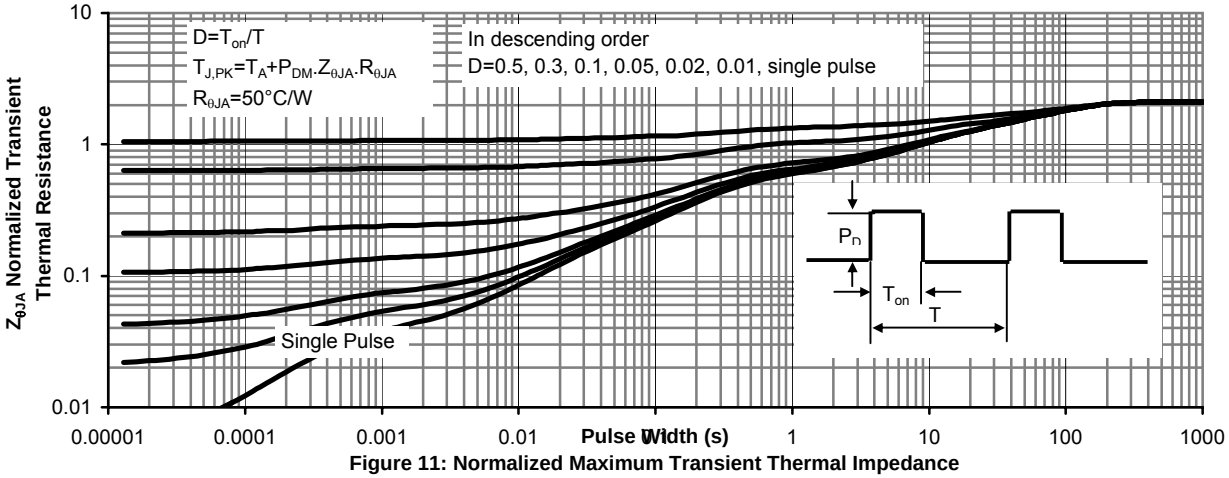

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